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PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Tsutomu KONO	02/17/2012
Keiji HANZAWA	02/21/2012
Takeshi MORINO	02/21/2012
Yuki OKAMOTO	02/21/2012
Noboru TOKUYASU	02/21/2012
Shinobu TASHIRO	02/21/2012

RECEIVING PARTY DATA

Name:	Hitachi Automotive Systems, Ltd.
Street Address:	2520 Takaba
City:	Hitachinaka-shi, Ibaraki
State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13393155

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: 108005.64299US

NAME OF SUBMITTER: Michael H. Jacobs

Total Attachments: 1

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PATENT REEL: 028201 FRAME: 0345 DP \$40.00 1339315

ASSIGNMENT

(譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI AUTOMOTIVE SYSTEMS, LTD., a corporation organized under the laws of Japan,

located at 2520, Takaba, Hitachinaka-shi, Ibaraki, Japan,

receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI AUTOMOTIVE SYSTEMS, LTD., its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

FLOW SENSOR AND MANUFACTURING METHOD OF THE SAME AND FLOW SENSOR MODULE AND MANUFACTURING METHOD OF THE SAME

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said HITACHI AUTOMOTIVE SYSTEMS, LTD.,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI AUTOMOTIVE SYSTEMS, LTD.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S) (発明者フルネームサイン)

1) TSOTOMU KONO (TSUTOMU KONO) February 17, 2012 2) Keili Hanzawa (Keiji HANZAWA) February 21, 2012 3) Takoshi Morino (Takeshi MORINO) February 21, 2012 4) Yuki Okeunto (Yuki OKAMOTO) February 21, 2012 5) Noboru Tokuyasu (Noboru TOKUYASU) February 21, 2012 6) Shinabu Jashiro (Shinobu TASHIRO) February 21, 2012

PATENT REEL: 028201 FRAME: 0346

Date Signed

(署名日)

RECORDED: 05/14/2012